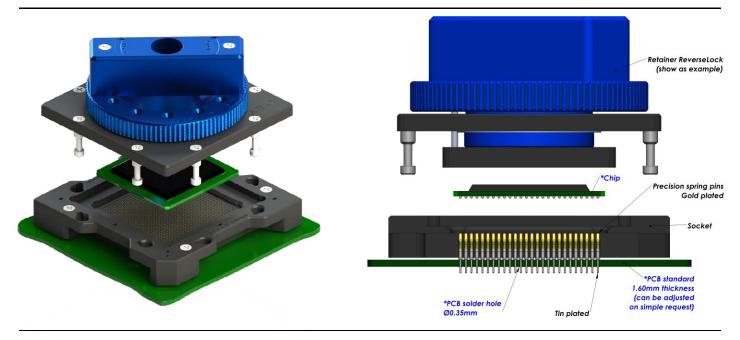
Through-hole (THT) soldering Test Socket

For BGA / Bumped chip / WLCSP / eMMC Package **0.50 mm pitch** (from 0.50 mm up to 0.79 mm)





E-tec Interconnect AG is the world leading Test socket manufacturer

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 0570			
Application	Through-hole technology	Force	30 gr
Mounting	THT	Current rating	1 A
Bandwidth (GHz@-1dB)	2.7 GHz	Capacitance pF	< 1 pF
Contact resistance	<100mOhm	Inductance nH	< 2 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	Through-hole	Mating cycles	100 K

How to order

BU # #### -0570 - # # # # # # 95 # Shape of tip Nbr of **Contact type Plating** Option code (see page 16-19) contacts 70 : Standard THT U:Concave D: Dead bug 95:Tin / Gold Depends on Options: M: Multi frames ballcount of chip U: Multi packages P: Pointed Other on request S: Custom opening slot S:Spring L: Locating pegs C: Crown A: Alignment plate Retention frame type (Lid) (see page 12-15) Grid code / H: Heatsink Config. code W: TwistLock S: ScrewLock F: Fan + Heatsink Will be given by the P: Thermal drain pad F:FastLock Q: Open QuickLock (<200 contacts) factory after receipt of the chip datasheet W: Transparent lid D: QuickLock (>200 contacts) B:SpringLock I : Steel retention lid H: Open Clamshell Alu (<200 contacts) M: Injection Molded ClamShell B: Aluminium retention lid J: Clamshell Alu (>200 contacts) R: ReverseLock T: Torque tool fixture L: Open Lever Clamshell Alu (>200 contacts) T: SlimLock G: Handling button

